

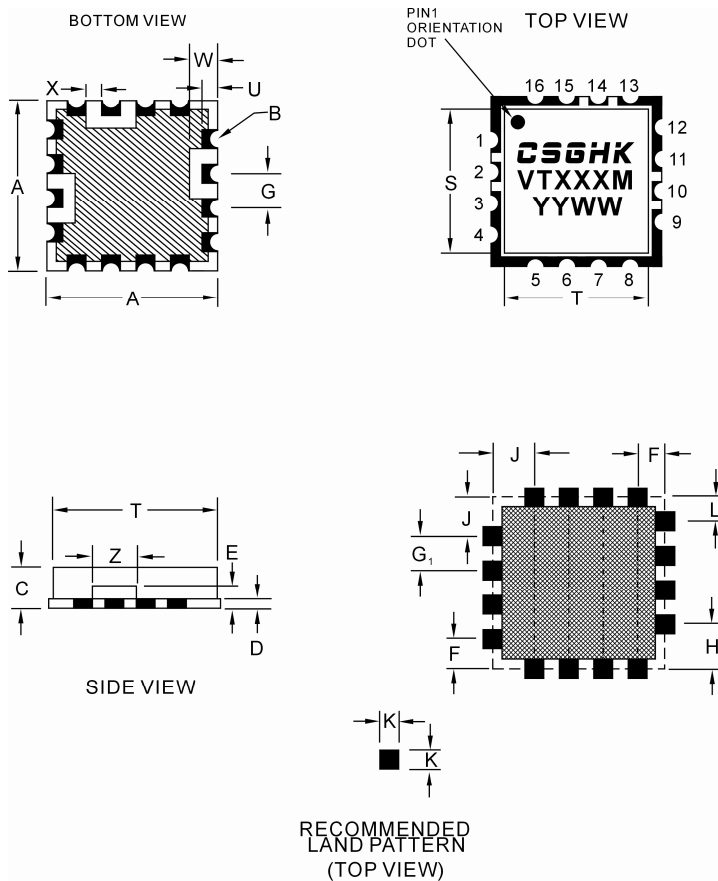
REVISIONS

NOTE, UNLESS OTHERWISE SPECIFIED:

1. THE METAL CASE IS GROUND
2. ALL HALF VIA CONTACTS ARE PLATED THRU FORM THE PAD ON THE TOP SIDE TO THE PAD ON THE BOTTOM SIDE OF THE BOARD.
3. HATCHED AREAS GROUND AND ARE COVERED WITH LPI SOLDER MASK OVER BARE COPPER. ALL CONTACT AREAS ARE PLATED. SIGNAL VIAS MAY BE LOCATED WITHIN GROUND PLANE.
4. SUBSTRATE MATERIAL: FR-4
5. XXXX REPRESENTS THE MODEL NUMBER.
6. YYWW IS THE DATA CODE.

PIN OUT FOR PLL	
PIN	APPLICATION
2	VT
10	RF OUT
14	VCC

ALL OTHER PINS ARE GROUND



SYMBOL	DIMENSION	
	MILLIMETERS	INCHES
A	12.7±0.25	0.50±0.010
B	R=0.50	R=0.019
C	3.50	0.138
D	0.99MAX	0.039MAX
E	1.75MAX	0.069MAX
F	2.16	0.085
G	2.54±0.08	0.100±0.003
G ₁	2.54	0.100
H	3.07	0.121
J	2.92	0.115
K	1.52	0.060
L	2.00	0.079
S	11.68	0.460
T	11.81	0.465
U	1.10	0.043
W	1.78	0.188
X	1.02	0.040
Z	3.49	0.137

	APPROVALS	DATA	CSG HK SK605 PACKAGE MECHANICAL PCB OUTLINE
DRAWN BY			
CHECKED BY			
PROCESS ENG			
QUALITY			